



3DP&I Panel Level Packaging (PLP) Panel TF

NA Standards Spring Meetings 2020

Thursday, April 2

13:30–14:30 (Pacific) via Web Conference

AGENDA

	Time
1 Welcome/Call to Order	13:30
1.1 Introductions and Announcements	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
2 Review of Previous Meeting Minutes	13:35
3 Ballot Review/Discussion	13:40
3.1 Document 6591 — Revision to SEMI 3D20-0719, Specification for Panel Characteristics for Panel Level Packaging (PLP) Applications	
4 Old Business	14:00
5 New Business	14:10
6 Action Item Review	14:15
7 Next Meeting and Adjournment	14:20
7.1 The next meeting is scheduled for Thursday, July 23, 2020 in conjunction with SEMICON West 2020. Time?	



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